

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Hiroshi HAMASAKI, et al.

SERIAL NO: New Application

GAU:

FILED: Herewith

EXAMINER:

FOR: LSI PACKAGE PROVIDED WITH INTERFACE MODULE AND METHOD OF MOUNTING THE SAME

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

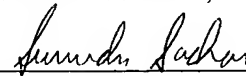
- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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DOCKET NO.: 249025US2SRD

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STATEMENT OF RELEVANCY

Reference AW on Form PTO-1449:

This reference relates to an Optical Interconnection Module. But these high frequency signals lines are fabricated on Printed Circuit Board.

Reference AX on Form PTO-1449:

This reference shows a similar optical interface module. But this module has an optical connector and no electrical connector.

Reference AY on Form PTO-1449:

This reference shows a similar optical interface module. But optical devices are mounted without coating and optical coupling are unstable.

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

249025US2SRD

SERIAL NO.

New Application

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Hiroshi HAMASAKI, et al.

FILING DATE

Herewith

GROUP

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO					
	AP					
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	Jerome EICHENBERGER, et al., "Multi-Channel Optical Interconnection Modules up to 2.5Gb/s/ch", Proc. 51 st 2001 ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE, 2001, Pages 880-885
	AX	Takashi YOSHIKAWA, et al., "Optical-interconnection as an IP macro of a CMOS Library", Proc. HOT INTERCONNECTS 9, SYMPOSIUM ON HIGH PERFORMANCE INTERCONNECTS, 2001, Pages 31-35
	AY	M. OKABE, et al., Proc. THE 16 TH JIEP ANNUAL MEETING, 2002, Vol 20B, No 10, Pages 283-284
	AZ	

☐ Additional References sheet(s) attached

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.